

Features

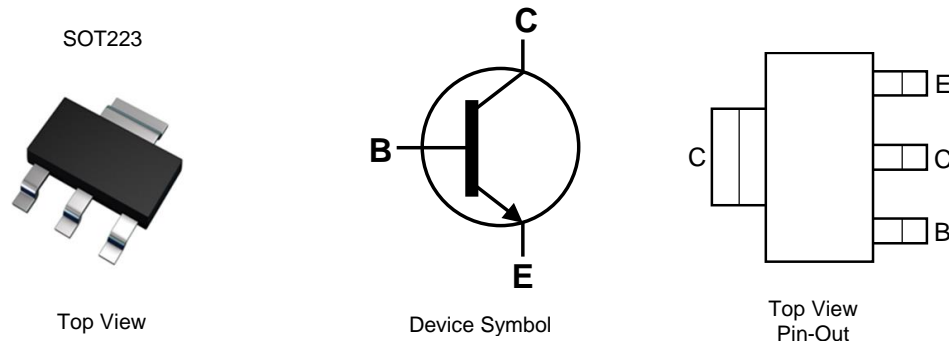
- $BV_{CEX} > 180V$
- $BV_{CEO} > 100V$
- $BV_{ECO} > 6V$
- $I_C = 3A$ High Continuous Current
- Low Saturation Voltage $V_{CE(sat)} < 100mV @ 1A$
- $R_{CE(sat)} = 85m\Omega$
- Complementary PNP Type: ZXTP19100CG
- **Lead-Free Finish; RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- **Qualified to AEC-Q101 Standards for High Reliability**
- **PPAP Capable (Note 4)**

Mechanical Data

- Case: SOT223
- Case Material: Molded Plastic, "Green" Molding Compound;
- UL Flammability Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish - Matte Tin Plated Leads; Solderable per MIL-STD-202, Method 208 (Ⓢ)
- Weight: 0.112 grams (Approximate)

Applications

- PSU Start-Up Circuit
- DC-DC Converters
- Motor Drive
- Relay, Lamp and Solenoid Drive

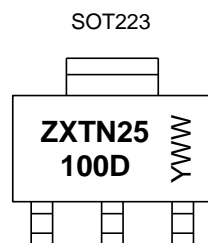


Ordering Information (Notes 4 & 5)

Product	Compliance	Marking	Reel size (inches)	Tape width (mm)	Quantity per reel
ZXTN25100DGTA	AEC-Q101	ZXTN25100D	7	12	1,000
ZXTN25100DGQTA	Automotive	ZXTN25100D	7	12	1,000

- Notes:
1. EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. All applicable RoHS exemptions applied.
 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
 4. Automotive products are AEC-Q101 qualified and are PPAP capable. Automotive, AEC-Q101 and standard products are electrically and thermally the same, except where specified. For more information, please refer to http://www.diodes.com/quality/product_compliance_definitions/.
 5. For packaging details, go to our website at <http://www.diodes.com/products/packages.html>.

Marking Information



ZXTN25100D = Product Type Marking Code
 YWW = Date Code Marking
 Y or \bar{Y} = Last Digit of Year (ex: 5= 2015)
 WW or \bar{WW} = Week Code (01~53)

Absolute Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V _{CBO}	180	V
Collector-Emitter Voltage (forward blocking)	V _{CEX}	180	V
Collector-Emitter Voltage	V _{CEO}	100	V
Emitter-Collector Voltage (reverse blocking)	V _{ECO}	6	V
Emitter-Base Voltage	V _{EBO}	7	V
Continuous Collector Current	I _C	3	A
Base Current	I _B	1	A
Peak Pulse Current	I _{CM}	3.5	A

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

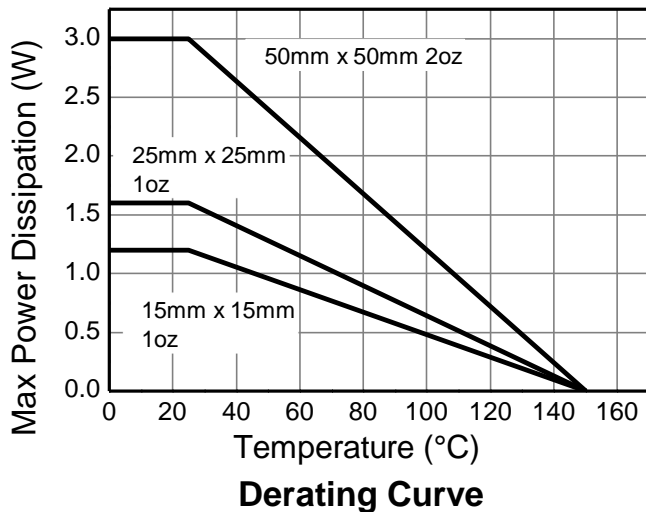
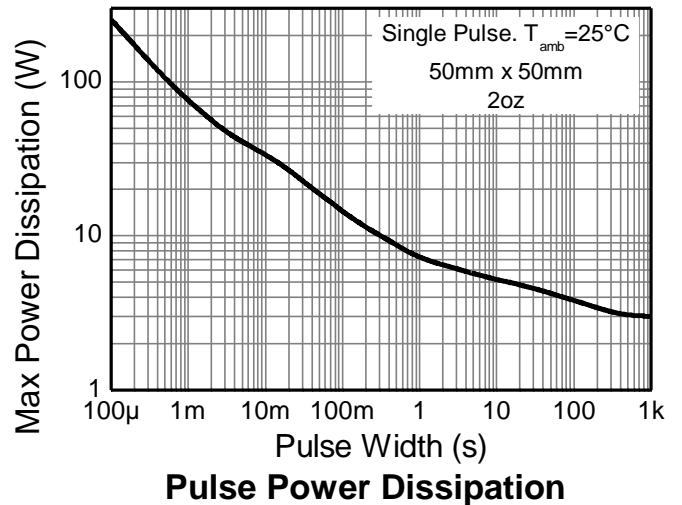
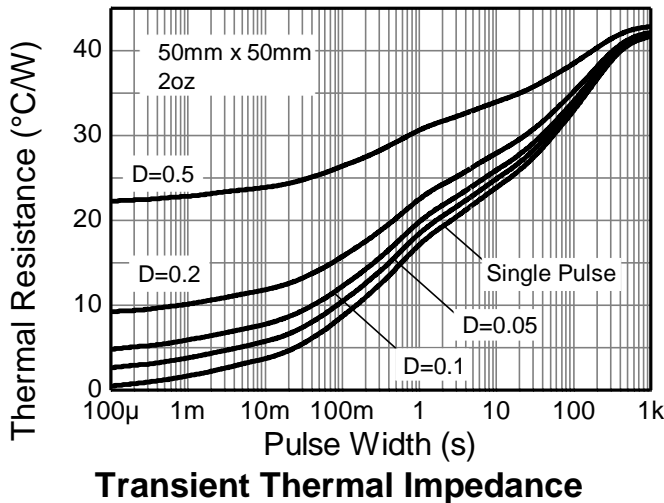
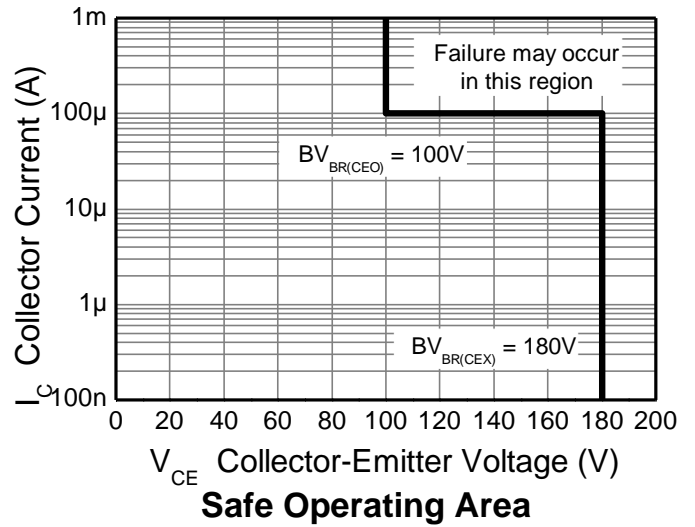
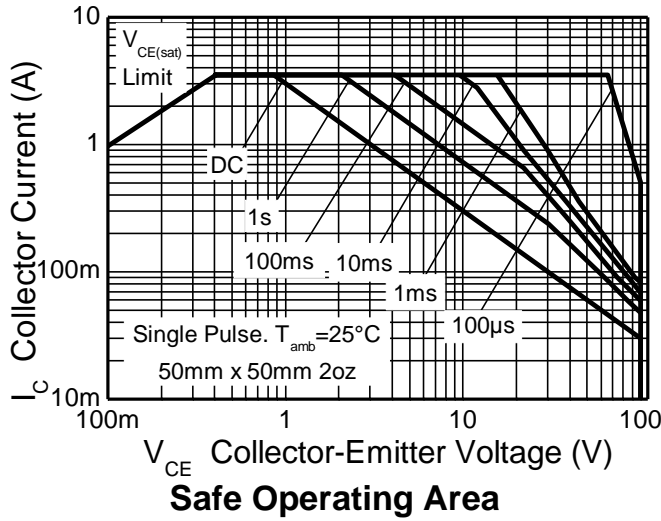
Characteristic	Symbol	Value	Unit
Power Dissipation Linear Derating Factor	P _D	1.2	W mW/°C
		9.6	
		1.6	
		12.8	
		3	
Thermal Resistance, Junction to Ambient	R _{θJA}	24	°C/W
		5.3	
		42	
		104	
Thermal Resistance, Junction to Lead	R _{θJL}	78	°C/W
		42	
		23.5	
Thermal Resistance, Junction to Solder Point	R _{θJS}	16	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

ESD Ratings (Note 11)

Characteristic	Symbol	Value	Unit	JEDEC Class
Electrostatic Discharge - Human Body Model	ESD HBM	4,000	V	3A
Electrostatic Discharge - Machine Model	ESD MM	400	V	C

- Notes:
- For a device mounted with the collector lead on 15mm x 15mm 1oz copper that is on a single-sided 1.6mm FR4 PCB; device is measured under still air conditions whilst operating in steady-state.
 - Same as Note 6, except the device is mounted on 25mm x 25mm 1oz copper.
 - Same as Note 6, except the device is mounted on 50mm x 50mm 2oz copper.
 - Same as Note 8 measured at t<5 seconds.
 - Thermal resistance from junction to solder-point (at the end of the collector lead).
 - Refer to JEDEC specification JESD22-A114 and JESD22-A115.

Thermal Characteristics and Derating Information (@T_A = +25°C, unless otherwise specified.)

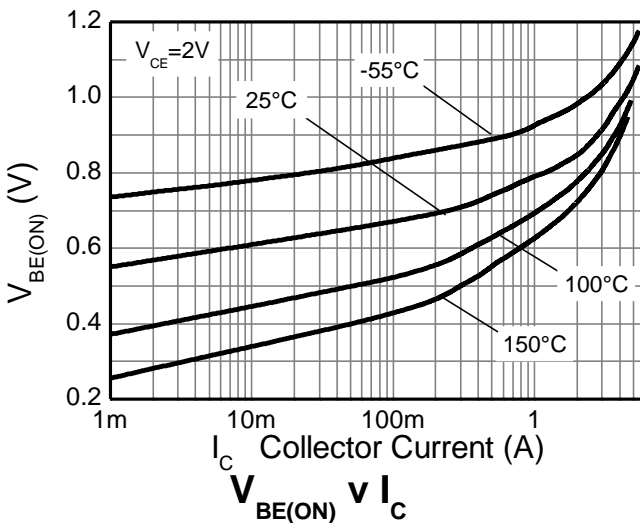
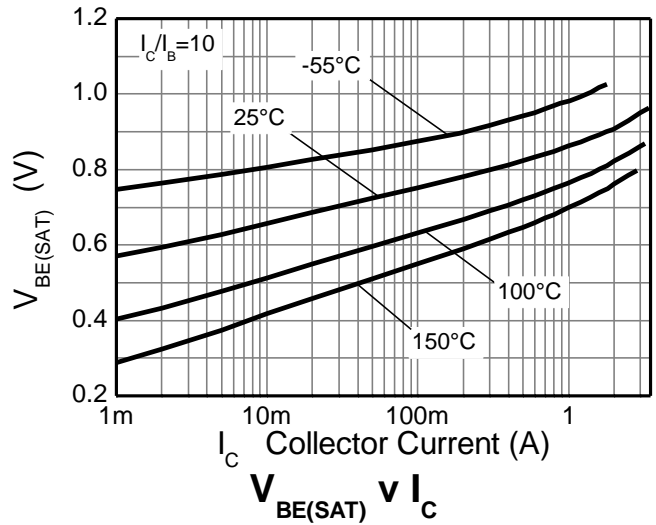
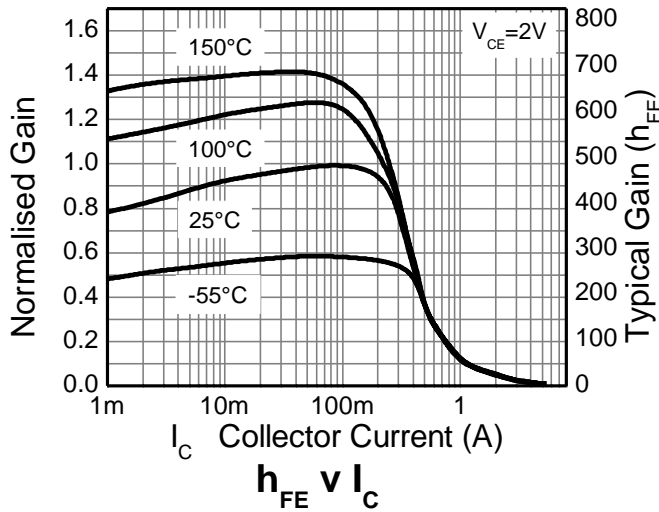
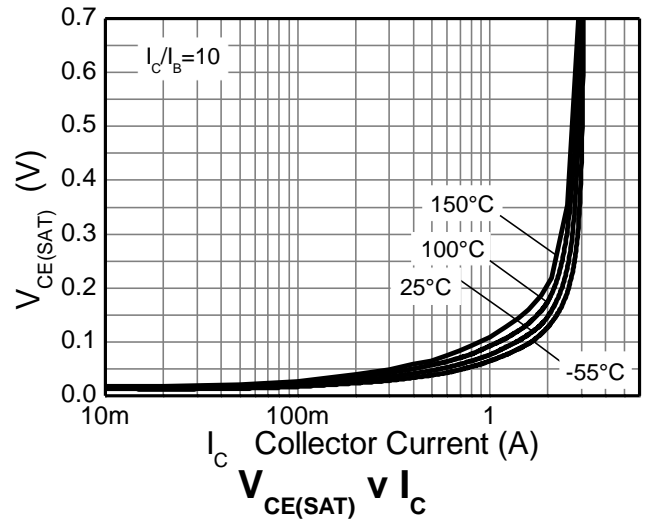
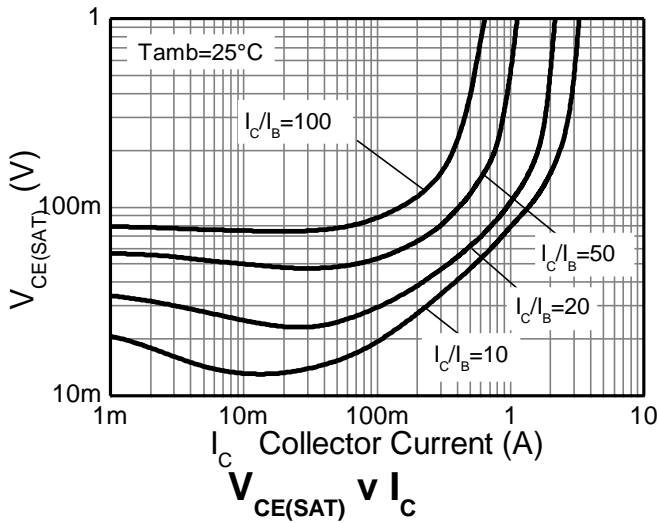


Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Collector-Base Breakdown Voltage	BV _{CBO}	180	220	–	V	I _C = 100μA
Collector-Emitter Breakdown Voltage (forward blocking)	BV _{CEX}	180	220	–	V	I _C = 100μA, R _{BE} < 1kΩ or -1V < V _{BC} > 0.25V
Collector-Emitter Breakdown Voltage (Note 12)	BV _{CEO}	100	130	–	V	I _C = 10mA
Emitter-Collector Breakdown Voltage (reverse blocking)	BV _{ECX}	6	8.2	–	V	I _C = 100μA, R _{BC} < 1kΩ or 0.25V < V _{BC} > -0.25V
Emitter-Collector Breakdown Voltage (reverse blocking)	BV _{EEO}	6	8.7	–	V	I _E = 100μA
Emitter-Base Breakdown Voltage	BV _{EBO}	7	8.3	–	V	I _E = 100μA
Collector Cut-Off Current	I _{CBO}	–	< 1	50	nA	V _{CB} = 180V
		–	–	0.5	μA	V _{CB} = 180V, T _A = 105°C
Collector-Emitter Cut-Off Current	I _{CEX}	–	–	100	nA	V _{CE} = 100V, R _{BE} < 1kΩ or -1V < V _{BC} > 0.25V
Emitter Cut-Off Current	I _{EBO}	–	< 1	50	nA	V _{EB} = 5.6V
Collector-Emitter Saturation Voltage (Note 12)	V _{CE(sat)}	–	120	170	mV	I _C = 0.5A, I _B = 10mA
		–	80	100	mV	I _C = 1A, I _B = 100mA
		–	215	345	mV	I _C = 2.5A, I _B = 250mA
		–	200	500	mV	I _C = 3A, I _B = 600mA
Base-Emitter Saturation Voltage (Note 12)	V _{BE(sat)}	–	1020	1100	mV	I _C = 3A, I _B = 600mA
Base-Emitter Turn-On Voltage (Note 12)	V _{BE(on)}	–	905	1000	mV	I _C = 3A, V _{CE} = 2V
DC Current Gain (Note 12)	h _{FE}	300	450	900	–	I _C = 10mA, V _{CE} = 2V
		120	170	–	–	I _C = 0.5A, V _{CE} = 2V
		40	60	–	–	I _C = 1A, V _{CE} = 2V
		–	10	–	–	I _C = 3A, V _{CE} = 2V
Current Gain-Bandwidth Product (Note 12)	f _T	–	175	–	MHz	V _{CE} = 10V, I _C = 50mA, f = 100MHz
Input Capacitance (Note 12)	C _{ibo}	–	154	250	pF	V _{EB} = 0.5V, f = 1MHz
Output Capacitance (Note 12)	C _{obo}	–	8.7	15	pF	V _{CB} = 10V, f = 1MHz
Delay Time	t _d	–	16.4	–	ns	I _C = 500mA, V _{CC} = 10V, I _{B1} = -I _{B2} = 50mA
Rise Time	t _r	–	115	–	ns	
Storage Time	t _s	–	763	–	ns	
Fall Time	t _f	–	158	–	ns	

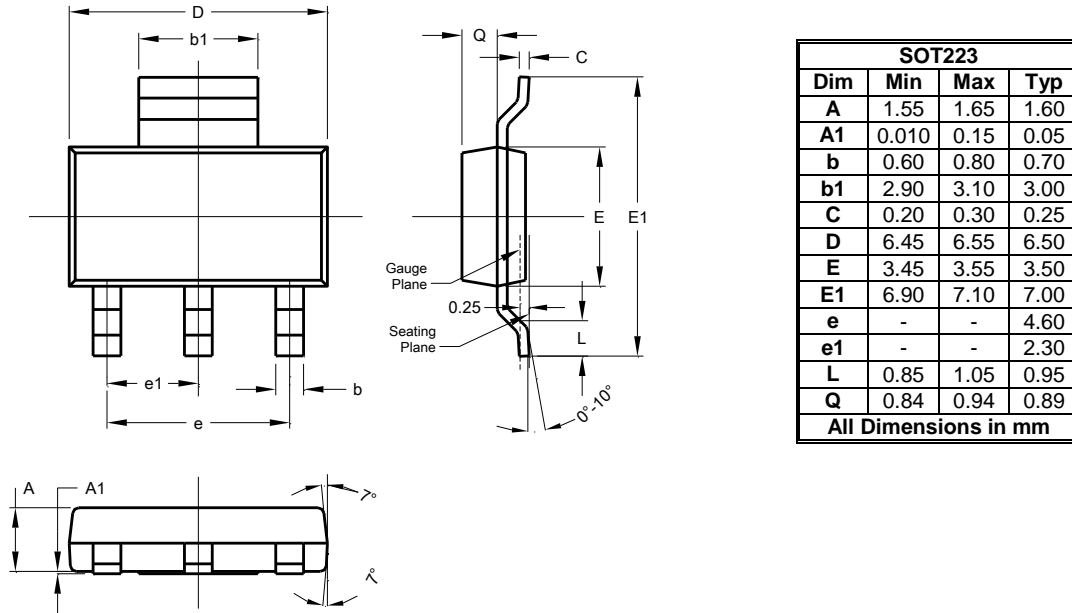
Note: 12. Measured under pulsed conditions. Pulse width ≤ 300μs. Duty cycle ≤ 2%.

Typical Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)



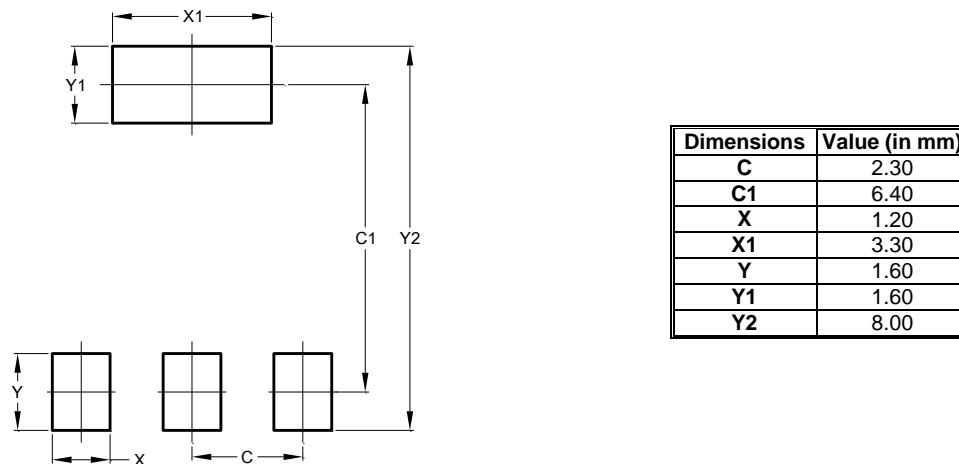
Package Outline Dimensions

Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for the latest version.



Suggested Pad Layout

Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for the latest version.



Note: For high voltage applications, the appropriate industry sector guidelines should be considered with regards to creepage and clearance distances between device terminals and PCB tracking.

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Офис по работе с юридическими лицами:

105318, г.Москва, ул.Щербаковская д.3, офис 1107, 1118, ДЦ «Щербаковский»

Телефон: +7 495 668-12-70 (многоканальный)

Факс: +7 495 668-12-70 (доб.304)

E-mail: info@moschip.ru

Skype отдела продаж:

moschip.ru

moschip.ru_4

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moschip.ru_9